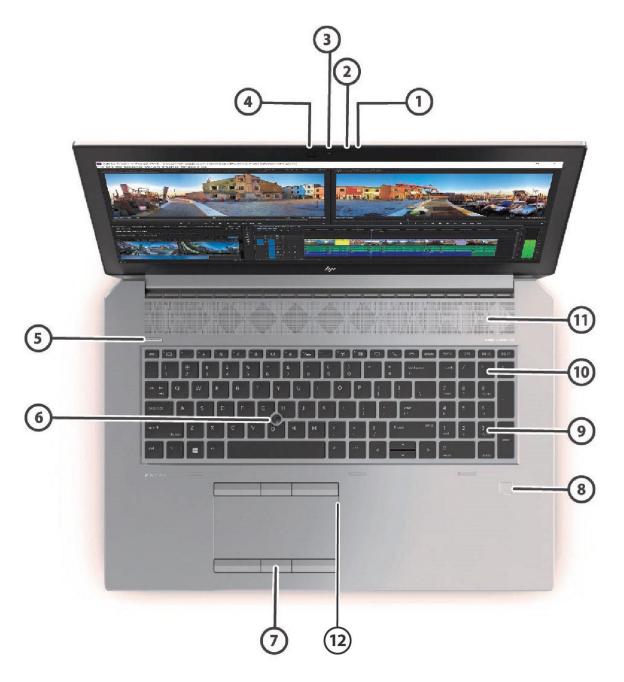
Overview

HP ZBook 17 G5 Mobile Workstation



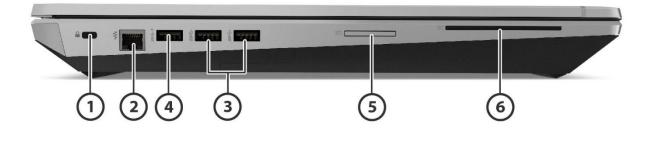
- 1. Microphone
- 2. IR camera
- 3. HP Privacy Camera
- 4. HP Privacy Camera shutter
- 5. Power button
- 6. Pointstick

- 7. 3-button touchpad
- 8. Fingerprint sensor
- 9. Numeric Keypad
- 10. Collaboration Keys
- 11. Speakers
- 12. Integrated Color Calibration Sensor



Overview

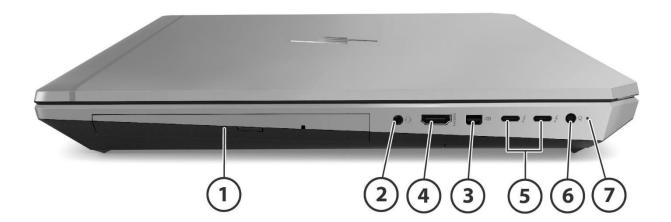
HP ZBook 17 G5 Mobile Workstation



Left View

- 1. Security cable slot
- 2. RJ-45/Ethernet
- 3. 2 USB 3.0

- 4. USB 3.0 charging port
- 5. SD Card reader
- 6. Smart Card Reader



Right View

- 1. Optical Disk Drive
- 2. Stereo microphone in / headphone-out combo jack
- 3. Mini DisplayPort™
- 4. HDMI 2.0 port

- 5. Thunderbolt[™] 3 ports
- 6. Power connector
- 7. Power LED



Overview



Buttom View

- 1. Fan Venting
- 2. Tool less access

3. Keyboard liquid drain

HP ZBook 17 G5 Mobile Workstation

QuickSpecs

0

Overview

At A Glance

- Full performance stylish industrial design, aluminum and magnesium-reinforced chassis with HP's Turbo Silver color provides optimal durability with minimal weight.
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke. HP Spill Resistant Keyboard with Durakeys to help protect keys from fading.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- HP Performance Advisor for optimal configuration, compatibility and performance
- Designed to pass MIL-STD-810G testing*.
- **Optional Workstation-caliber graphics:** •
 - NVIDIA[®] Quadro[®] discrete graphics featuring NVIDIA[®] Optimus technology:
 - NVIDIA[®] Quadro[®] P1000 (4GB GDDR5)
 - NVIDIA[®] Ouadro[®] P2000 (4GB GDDR5)
 - NVIDIA® Quadro® P3200 (6GB GDDR5)
 - NVIDIA® Quadro® P4200 (8GB GDDR5) .
 - NVIDIA[®] Quadro P5200 (16GB GDDR5)
 - AMD RadeonPro[™] WX 4170 (4GB GDDR5) featuring AMD Enduro[™] technology
- Intel® Integrated graphics: Intel® UHD Graphics 630 integrated on Core™ i7. Intel® UHD Graphics P630 integrated on Xeon[®] processors.
- Choice of 8th generation Intel[®] Core[™] i5 guad-core and Intel[®] Core[™] i7 hexa-core or Intel[®] Xeon[®] hexa-core processors • with option Intel[®] vPro[™] technology.
- Populate up to four SODIMM slots supporting up to 64 GB DDR4-2667MHz dual channel memory. Up to 64GB ECC DDR4-2667MHz dual channel memory available with Intel® Xeon® processors.
- Supports multi-display, including up to four (4) displays without a docking solution, with hybrid graphics enabled. Supports up to six (6) displays or (2) 4K displays with HP Thunderbolt[™] Dock G2 (sold separately), with hybrid graphics enabled.
- Choice of 17.3-inch diagonal LED-backlit displays:
 - HD+ IPS eDP anti-glare, 220 nits 85% sRGB (1600x900) 0
 - FHD IPS eDP anti-glare 300 nits with ambient light sensor 100% sRGB (1920x1080) 0
 - UHD IPS eDP + PSR Touch-screen 400 nits ambient light sensor 100% sRGB (3840x2160) 0
 - HP DreamColor Technology, UHD IPS eDP + PSR , anti-glare 400 nits, 100% AdobeRGB with 10-bit color (3840x2160) featuring Integrated Color Calibration Sensor on ClickPad to ensure color accuracy
- Two (2) Thunderbolt[™] 3 ports (supporting DP 1.3, USB 3.1, PCIe Gen 3 devices) on the new USB-C[™] connector. for high speed data/video/audio transfer support.
- Flexible wireless connectivity options:
 - Intel[®] Dual Band Wireless-AC 9560 802.11 AC/a/b/g/n (2x2) WiFi and Bluetooth 5.0 combo adaptor (non-vPro™) 0 or, Intel® Dual Band Wireless-AC 9560 802.11 AC/a/b/g/n (2x2) WiFi and Bluetooth 5.0 combo adaptor (vPro™) 0
 - Optional integrated wireless 4G (LTE) mobile broadband module support
- Optimize your audio experience for conference calls and remote collaboration with optional HD webcam, dual-array microphones, premium speakers, HP Noise Cancellation Software, HP Audio Boost, and audio. Custom-tuned by HP and Bang & Olufsen optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal-clear dialog without distortion at high volume, and new discrete amp.
- HP Long life battery solution: 6-cell (96 WHr) supporting HP Fast Charge capability •
- Four (4) dedicated drive slots, three (3) M.2 slots, and one (1) 2.5" drive bays; Optical disk drive bay with option for extra Storage module supporting up to 10TB of data.
- Enterprise grade security features including HP Client Security Manager, HP SureClick, HP WorkWise, HP SureView, and HP SureStart self-healing BIOS, TPM 2.0, Touch Fingerprint Sensor, Integrated Smart Card Reader, BIOS Preboot power on, and Drive Encryption preboot option. HP BIOS technology, including HP Sure Start to identify and recover from unknown **BIOS** attacks.



Overview

*MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64 ¹ Windows 10 Pro for Workstations 64 Windows 10 Home 64 ¹ FreeDOS 2.0
Supported	Windows 10 Enterprise 64 ¹ Red Hat® Enterprise Linux® (REHL) 7 Ubuntu Linux 16.04

¹Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com

PROCESSOR

Intel[®] Core[™] i7+ 8750H processor (Core i7 and 16GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 630 (2.2 GHz base frequency, up to 4.1 GHz with Intel[®] Turbo Boost Technology, 9 MB cache, 6 cores)

Intel[®] Core[™] i7-8750H with Intel[®] UHD Graphics 630 (2.2 GHz base frequency, up to 4.1 GHz with Intel[®] Turbo Boost Technology, 9 MB cache, 6 cores)

Intel[®] Core[™] i5+ 8300H (Core i5 and 16GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 630 (2.3 GHz base frequency, up to 4.0 GHz with Intel[®] Turbo Boost Technology, 8 MB cache, 4 cores)

Intel[®] Core™ i5-8300H with Intel[®] UHD Graphics 630 (2.3 GHz base frequency, up to 4.0 GHz with Intel[®] Turbo Boost Technology, 8 MB cache, 4 cores)

Intel[®] Core[™] i5+ 8400H vPro[™] processor (Core i5 and 16GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 630 (2.5 GHz base frequency, up to 4.2 GHz with Intel[®] Turbo Boost Technology, 8 MB cache, 4 cores)

Intel[®] Core™ i5-8400H vPro™ processor with Intel[®] UHD Graphics 630 (2.5 GHz base frequency, up to 4.2 GHz with Intel[®] Turbo Boost Technology, 8 MB cache, 4 cores)

Intel[®] Core[™] i7+ 8850H vPro[™] processor (Core i7 and 16GB Intel[®] Optane[™] memory) with Intel[®] UHD Graphics 630 (2.6 GHz base frequency, up to 4.3 GHz with Intel[®] Turbo Boost Technology, 9 MB cache, 6 cores)

Intel[®] Core™ i7-8850H vPro™ processor with Intel[®] UHD Graphics 630 (2.6 GHz base frequency, up to 4.3 GHz with Intel[®] Turbo Boost Technology, 9 MB cache, 6 cores)

Intel[®] Xeon[®] E-2176M vPro[™] processor with Intel[®] UHD Graphics P630 (2.7 GHz base frequency, up to 4.4 GHz with Intel[®] Turbo Boost Technology, 12 MB cache, 6 cores)

Intel[®] Xeon[®] E-2186M vPro[™] processor with Intel[®] UHD Graphics P630 (2.9 GHz base frequency, up to 4.8 GHz with Intel[®] Turbo Boost Technology, 12 MB cache, 6 cores)

*Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. *Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

Note: In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com



Features

CHIPSET

Mobile Intel® CM246

INTEL[®] CORE™ I5 WITH VPRO™/CORE I7 WITH VPRO™/XEON[®] WITH VPRO™ TECHNOLOGY CAPABLE

Intel[®] Core[™] i5 with vPro[™], Core[™] i7 with vPro[™] and XEON[®] with vPro[™] technology is a selectable feature that is available on units configured with select processors, a qualified Intel[®] WLAN module and a preinstalled Windows[®] operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel[®] Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel[®] Core[™] i5 with vPro[™]/Core[™] i7 with vPro[™]/Xeon[®] with vPro[™] technology, such as Intel[®] Active Management technology and Intel[®] Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel[®] Core[™] i5 with vPro[™]/Core i7 with vPro[™]/XEON[®] with vPro[™] technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.



Features

GRAPHICS

Intel[®] Integrated Intel[®] UHD graphics 630^{1,2}; Intel[®] UHD graphics P630^{1,2};

Discrete³

AMD RadeonPro[™] WX 4170 with 4 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA[®] Quadro[®] P1000 with 4 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA[®] Quadro[®] P2000 with 4 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA[®] Quadro[®] P3200 with 6 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P4200 with Max-Q Design 8 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA[®] Quadro[®] P5200 with Max-Q Design 16 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NOTE 1: UHD content required to view UHD images.

NOTE 2: Intel[®] HD graphics 630 is configurable as a standalone graphics option; Intel[®] HD graphics P630 only used when NVIDIA[®] Optimus[™] Technology is enabled.

NOTE 3: NVIDIA[®] Quadro[®] mobile professional graphics support up to four independent displays when using a HP ZBook Dock with Thunderbolt[™] 3 (sold separately) or DP 1.2 hubs with MST. AMD RadeonPro[™] professional graphics support up to six independent displays when using an HP ZBook Dock with Thunderbolt[™] 3 (sold separately) or DP 1.2 hubs.

NOTE: Intel[®] HD Graphics 630 integrated on Core[™] i7 and Core[™] i5 processors. Intel[®] HD Graphics P630 integrated on Xeon[®] processors.

DisplayPort™ 1.3 protocol features supported on Thunderbolt™ 3 ports:

- Legacy displays (HDMI, DVI, VGA) may be attached to Thunderbolt™ port with the use of a certified dongle.
- DisplayPort[™] monitors capable of supporting DisplayPort[™] 1.3 may be directly attached to the Thunderbolt[™] port to achieve HBR2 with the use a dongle.
- Thunderbolt[™] 3 enabled monitors may be directly attached to the Thunderbolt[™] port to achieve HBR2 and MST.
- DisplayPort[™] 1.3 MST feature ("daisy-chain" feature) is supported through Thunderbolt[™] 3 port on Thunderbolt[™] 3 enabled devices or DisplayPort[™] 1.3 monitors (requires monitor with DisplayPort[™] 1.3 MST capability) with the use of a dongle.
- Up to 2 streams (eight lanes) of DisplayPort[™] 1.3 are supported over a single Thunderbolt[™] 3 port. Up to (2) 4K displays 24/30-bit color depth at 60 Hz or (1) 5K display supported over a single Thunderbolt[™] 3 port. (Requires Intel[®] certified Thunderbolt[™] cable).
- DisplayPort[™] 1.3 w/MST (Multi-stream Transport): Supports resolutions up to Full 4K, 24/30-bit color depth at 60 Hz, and WUXGA (1920 x1200) monitors, 24/30-bit color depth at 120 Hz.

*Thunderbolt[™] 3 is superset port supporting DisplayPort[™] 1.3, USB 3.1 Gen 2, and PCIe Gen 3 devices over the new USB-C[™] connector. Install all the latest drivers for your Thunderbolt[™] device before connecting the device to the Thunderbolt[™] port.



Features

Multi-Display Support

Without HP Thunderbolt Dock G2:

HP ZBook 17 with hybrid graphics and without the use of the ZBook dock supports up to a maximum of four independent displays. These four displays are the internal panel plus three external displays connected to the Mini DisplayPort[™] 1.3 and two of the three following ports: HDMI 2.0, Thunderbolt[™] 3, Thunderbolt[™] 3. HP ZBook 17 configuration with Intel[®] integrated graphics and without the use of the ZBook dock supports up to a maximum of three independent displays. Any three-display combination of the system panel: HDMI, Thunderbolt[™] 3, Thunderbolt[™] 3.

With HP Thunderbolt Dock G2:

The HP Thunderbolt Dock G2 has Thunderbolt[™] 3 port, VGA, two DisplayPort[™] 1.3, and a USB-C port. When used together with the HP ZBook 17 configuration with hybrid graphics, a maximum of 6 independent displays are supported. These six displays are internal panel, one external display connected to the system's HDMI port and four external displays connected to the ZBook dock's Thunderbolt[™] 3, VGA, and two DisplayPort[™] ports. When used together with the HP ZBook 17 configuration with Intel[®] integrated graphics, a maximum of 3 independent displays are supported. Any three display combination of the system panel, system ports and ZBook Dock ports.



Features

DISPLAY

Internal

- 17.3" diagonal HD+ IPS eDP anti-glare LED-backlit, 220 nits 85% sRGB (1600x900)
- 17.3" diagonal FHD IPS eDP anti-glare LED-backlit, 300 nits with ambient light sensor 100% sRGB (1920x1080)
- 17.3" diagonal UHD IPS eDP + PSR Touch screen with Corning[®] Gorilla[®] Glass 4, LED-backlit, 400 nits, ambient light sensor 100% sRGB (3840x2160)
- HP Dream Color Display, 17.3" diagonal UHD IPS eDP + PSR, anti-glare, RG phosphors LED-backlit, 400 nits, 100% AdobeRGB with 10-bit color (3840x2160) featuring Integrated Color Calibration Sensor on ClickPad to ensure color accuracy.

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

(1) Optical disk drive

Blu-ray R/RE DVD +/-RW SuperMulti DL Drive 2.5" 2 TB SATA SSHD (Hybrid Drive) (8 GB cache) in Optical Bay Carrier

(3) M.2

SATA SED Solid State Drives*

256 GB SATA Self Encrypting Drive (SED) Solid State Drive 512 GB SATA FIPS 140-2 Solid State Drive

NVMe Solid State Drives

16 GB Intel[®] Optane[™] memory^{**, ***} 256GB PCIe (NVMe) TLC Solid State Drive 360GB PCIe (NVMe) TLC Solid State Drive 512GB PCIe (NVMe) TLC Solid State Drive 1 TB PCIe (NVMe) TLC Solid State Drive 2 TB PCIe (NVMe) TLC Solid State Drive 256GB PCIe (NVMe) TLC SED Solid State Drive 512GB PCIe (NVMe) TLC SED Solid State Drive

(1) 2.5" Storage Bay Drives*

2 TB 5400 rpm SATA Hard Disk Drive 2 TB SATA SSHD (Hybrid Drive) (8 GB cache) 1 TB SATA SSHD (Hybrid Drive) (8 GB cache) 1 TB 7200 rpm SATA Hard Disk Drive 500 GB 7200 rpm SATA Hard Disk Drive 500 GB SATA SSHD (Hybrid Drive) (8 GB cache) 500 GB 7200 rpm SATA Self Encrypting Drive (SED) Hard Disk Drive 500 GB 5400 rpm SATA Self Encrypting Drive (SED) FIPS 140-2 Hard Disk Drive 256GB SATA Solid State Drive 1 TB SATA Solid State Drive

HP 3D DriveGuard (Windows only)

The hard drive is mounted directly to the notebook frame, reducing the transmission of shock to the hard drive. Uses threeaxis digital motion detection with intelligent sensitivity to help protect the hard drive during normal use from shock and vibration. The digital accelerometer temporarily halts all data transfer and parks the hard drive when abrupt motion is



Features

detected.

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

Must be configured with either a Hard Disk Drive or a Hybrid Drive. Cannot be configured with an additional M.2 SSD. *Intel[®] Optane[™] memory system acceleration does not replace or increase the DRAM in your system

DRIVE CONTROLLERS

(1) 2.5" Storage Bays:HP Z Turbo Drive:RAID:NOTE: Raid 0, 1 supported only on SATA drives.

SATA-3 or SATA-2 for HDD PCIe NVMe SSD and SATA-3 for SSD 0, 1 supported*

MEMORY

Standard

64 GB DDR4 ECC or Non-ECC SDRAM (With transfer rates up to 2667MT/s¹) Four SODIMM slots supporting dual-channel memory; two SODIMMS slots are customer accessible or upgradeable 4 GB, 8GB and 16 GB SODIMMs (for Intel[®] Core[™] Processors) 8GB and 16 GB ECC SODIMMs (for Intel[®] XEON[®] Processors)

Maximum

Upgradeable to 64 GB with optional 16 GB SODIMMs in all 4 SODIMM slots

Dual-channel Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

NOTE 1: Intel[®] allows architectures designed with four DIMM slots to run at 2400 MT/s

NOTE: Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NETWORKING/COMMUNICATIONS

Communications*

Intel® I219-LM Gigabit* Network Connection (vPro configurations)

Wireless

Support for a broad range of secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Optional Broadband Wireless (WWAN) requires a Windows[®] operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth[®] is also available (factory configurable only) and can be combined with any of the supported wireless LAN and wireless WAN options.

802.11 Wireless LAN options**

Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo, vPro™ Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo, non-vPro™

Wireless WAN - Mobile Broadband options***



Features

Intel[®] XMM[™] 7360 LTE-Advanced HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module

Near Field Communication¹

NFC Mirage WNC XRAV-1 (NXP NPC300 I2C 10mmx17mm)

*The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

**Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

*** WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

¹Sold separately or as an optional feature.

AUDIO/MULTIMEDIA

Audio¹

Audio custom-tuned by HP and Bang & Olufsen, dual stereo speakers Dual array digital microphone Optional World Facing microphone Functions keys for volume up and down Combo microphone/headphone jack HD audio; featuring HP Noise Cancellation Software, HP Clear Sound Amp and Skype for Business Certification

Webcam*,**

Optional HP Privacy Camera (720p HD webcam)

Optional HP Privacy Camera (720p HD webcam) IR camera for face authentication with Windows Hello

- Privacy Camera features sliding camera shutter (non-touch only)
- HD format (widescreen)
- Supports videoconferencing and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing
- Improved low light sensitivity
- Improved dynamic range

* HD content required to view HD images.

**Optional or add-on feature.

Note 1: Dual-microphone array when equipped with optional webcam and optional world facing microphone

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS



Features

Keyboard

Full-size, spill-resistant backlit HP Premium Collaboration Keyboard to manage most commonly used conferencing functions with a single keystroke with Durakeys to help protect keys from fading, featuring function key control and numeric keypad

Pointing Devices

Clickpad with Image sensor touchpad with on/off button, two-way scroll, gestures, three buttons; Pointstick with three additional pointstick buttons

Buttons and Function Keys

Discrete buttons provide easy access to the following features:

- F1 Display Switching
- F2 HP Sure View (if configured)
- F3 Brightness Down
- F4 Brightness Up
- F5 Speaker mute
- F6 Volume down
- F7 Volume up
- F8 Microphone mute
- F9 Keyboard backlight
- F10 NumLock
- F11 Wireless on/off
- F12 Calendar
- F13 Share screen
- F14 Call
- F15 End Call



Features

SOFTWARE AND SECURITY

Preinstalled Software with Windows® Operating System

BIOS

HP BIOSphere Gen4¹ HP Sure Start Gen4² HP DriveLock | HP Automatic DriveLock BIOS Update via Network Master Boot Record Security Power On Authentication Secure Erase³ Absolute Persistence Module⁴ Pre-boot Authentication Measured Boot HP Sure Click HP LAN-WLAN Protection

Multi Media

Cyberlink Power MediaPlayer CMIT

Communication / Connectivity

HP Mobile Connect Pro⁵ Native Miracast Support⁶ HP MAC Address Manager (select models only) HP Host Based Mac Address HP Wireless Wakeup (select models only) HP SureConnect

HP Value Add Software

HP 3D DriveGuard ⁶ HP Hotkey Support HP Recovery Manager HP Jumpstart HP Support Assistant¹² HP Noise Cancellation Software HP Remote Graphics Software

Microsoft Products

Buy Office Bing Search Skype⁸

Manageability

HP Driver Packs⁹ HP SoftPaq Download Manager (SDM) HP System Software Manager (SSM)⁹ HP BIOS Config Utility (BCU)⁹ HP Client Catalog⁹ HP Manageability Integration Kit for Microsoft SCCM¹⁰ HP Image Assistant LANDESK Management¹¹

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Client Security Software



Features

- HP Client Security Suite Gen3¹³
- HP Security Manager (including Credential Manager and Password Manager¹⁵)
- HP Fingerprint Sensor
- IR Camera with Windows Hello
- Power On Authentication
- Device Access Manager
- Microsoft Defender ¹⁴

HP Value Add Software – Available via HP.com

HP ePrint Driver + JetAdvantage⁷ HP Performance Advisor

For Windows 10, Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified. For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1. HP BIOSphere Gen4 requires Intel[®] or AMD 8th generation processors.
- 2. HP Sure Start Gen4 is available on HP Z Workstations products equipped with 8th generation Intel® or AMD processors.
- 3. HP Secure Disk Erase is for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
- 4. BIOS Absolute Persistence module is shipped turned off, and will be activated when customers purchase and activate a subscription. Service may be limited. Check with Absolute for availability outside the U.S. The optional subscription service of Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. If Data Delete is utilized, the Recovery Guarantee payment is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either create a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 5. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to http://www.hp.com/go/mobileconnect
- 6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast
- 7. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/eprintcenter). Requires optional broadband module. Broadband use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
- 8. Skype is not offered in China.
- 9. Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 10. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 11. Subscription required.
- 12. Requires Windows and Internet Access
- 13. Requires Windows and Intel® 7th generation processors.
- 14. Opt in and internet connection required for updates
- 15. HP Password manager requires Windows.

Workstation ISV Certifications

See the latest list of certifications at: http://www.hp.com/go/isv



Features

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: http://www.hp.com/go/performanceadvisor

Other Standard Security Features

BIOS Update via Network Pre-boot Authentication SATA 0,1 port disablement (viaBIOS) **RAID** configurations Serial, USB enable/disable (viaBIOS) Power-on password (viaBIOS) Setup password (viaBIOS) Support for chassis padlocks and cable lock devices Measured Boot HP Sure Click¹ **Integrated Smart Card Reader One-Step Logon** Security lock slot Support for Intel® AT TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified) HP Sure Run² HP Sure Recovery³

ТРМ

Model: Infineon SLB9670 Version: 7.63.3353.0 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes with Convert TPM to 2.0 (FIPS 140-2) option

Fingerprint Sensor (Optional)

Voltage: 3.0-3.6V Operating temperature: -20° - 85°C Imaging current: 31mA Wake on finger current: 40 uA Capture rate: 30ms/frame ESD Resistance: IEC 6100-4-2 4B (+/-15KV) Detection Matrix: 363 dpi, sensing area 8x8 mm

Smartcard Reader

Model number: Alcor AU9560

Optional Security Features

HP Fingerprint Sensor (optional)⁴ IR Camera with Windows Hello Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS technology. GPS functionality requires HP Mobile Broadband Module.

* The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a



Features

subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.

- 1. HP Sure Click is available on select platforms only as a web-download from the HP Support website, is preinstalled on select HP platforms and supports Microsoft[®] Internet Explorer and Chromium[™]. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.
- 2. HP Sure Run is available on HP Elite and ZBook products equipped with Intel[®] or AMD[®] 8th generation processors
- 3. HP Sure Recover is available on HP Elite and ZBook PCs with 8th generation Intel[®] or AMD processors and requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data
- 4. Finger Sensor is optional

HP CENTRAL MANAGEMENT

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidently compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks. This helps to future-proof your technology and business.

An optional fingerprint sensor and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.

POWER

Power Supply

HP 200W Slim Smart AC adapter (165 x 79 x 25.4 mm)

Primary Battery

HP Long Life 6-cell Polymer Battery (96 WHr) *

NOTE: Battery is internal and is replaceable by the customer

Battery Life

Battery life up to 17 hours for UMA graphics only configuration **

Battery life up to 16.5 hours for Hybrid graphics configuration **



Features

System Standby Time

Up to 2.3 weeks***

* Available with 3-year limited warranty only

** Windows® 10 MM014 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.
*** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

NVIDIA[®] Optimus or AMD Enduro[™] technology Hibernation Standby ACPI compliance

ENVIRONMENTAL

US ENERGY STAR[®] IT ECO declaration EPEAT[®] Gold registered* Low Halogen**

* EPEAT [®] Gold registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options. **External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

WEIGHTS & DIMENSIONS

Weight

Starting at 7.0 lb. (3.2kg.) **Dimensions** (w x d x h) 16.4 in x 11.35 in x 1.3 in 416 mm x 288 mm x 33.5 mm

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes Quad Core CPU, FHD, Intel[®] HD graphics, 8GBx1 SODIMM, HP Z Turbo Drive, wLAN/BT, FPR, 9-cell battery, no wWAN.

PORTS/SLOTS

Ports Left side: 1) RJ-45 (Ethernet) (1) USB 3.0 Charging Port (2) USB 3.0 (1) Security lock slot

Right side:



Features

(1) Power connector;

- (2) Thunderbolt™ 3* (Supporting DisplayPort™ 1.3, USB 3.1 Gen2, PCIe Gen 3 devices)
- (1) Mini DisplayPort™ 1.3

(1) HDMI 2.0

(1) Stereo microphone in / headphone-out combo jack;

Thunderbolt™ 3

Thunderbolt[™]3 ports supports DisplayPort[™] 1.3, USB 3.1 Gen 2, and PCIe Gen 3 devices over the new USB-C port connector. The port is compatible with existing DisplayPort[™] displays, devices, and cables. Install all the latest drivers for your Thunderbolt[™] device before connecting the device to the Thunderbolt[™] port. Thunderbolt[™] cable and Thunderbolt[™] device (sold separately) must be compatible with Windows[®]. To determine whether your device is Thunderbolt[™] Certified for Windows, see https://thunderbolttechnology.net/products.

Digital Media Slots

(1) SD UHS-II Flash Media slot (Supports next generation SD (Secure Digital) and is backward compatible to SDHC, SDXC)
 (1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Optional* HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

*Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5 V	
	Average Operating Power	r DreamColor	25 W Windows® 10 (64-bit)
		Without DreamColor	16.8 W Windows® 10 (64-bit)
	Max Operating Power	< 200 W	
Temperature	Operating	32° to 95° F (0° to 35° C)	
	Non-operating	-4° to 140° F (-20° to 60° C)	
Relative Humidity	Operating	10% to 90%, non-condensing	
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet l	oulb temperature
Shock	Operating	40 G, 2 ms, half-sine	
	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)	
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)	
Industry Standard	UL	Yes	
Certifications	CSA	Yes	
	FCC Compliance	Yes	
	ENERGY STAR®	Select models*	
	EPEAT	Gold **	
	ICES	Complete	
	Australia /	Complete	
	NZ A-Tick Compliance		
	כככ	Complete	
	Japan VCCI Compliance	Complete	
	KC	Complete	
	BSMI	Complete	
	CE Marking Compliance	Complete	
	MIL STD 810G	Complete *** STAP qualified are identified as HP 7Book 17 G	

* Configurations of the HP ZBook 17 that are ENERGY STAR qualified are identified as HP ZBook 17 G5 ENERGY STAR[®] on HP websites and on http://www.energystar.gov.

** EPEAT[®] Gold registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

*** MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.



Technical Specifications – Displays

DISPLAYS

(III)

17.3" diagonal HD+ AG	Dimensions (W × H)	398.6*251 (mm)	
LED IPS 85% sRGB (1600 X	Weight	550g max	
900) (220 nits)	Diagonal Size	17.3 in (43.9 cm)	
	Surface Treatment	Anti-glare	
	Contrast Ratio	400:1 (typical)	
	Refresh Rate	60 Hz	
	Brightness*	220 nits (typical)	
	Pixel Resolution	Format	1600 x 900
		Configuration	RGB Stripe
	Backlight	LED	
	PPI	106	
	Viewing Angle		Right/Down/Up) (typical)
		= 1 billion bytes. TB = 1	trillion bytes. Actual formatted capacity is less. Up to
17.3" diagonal FHD AG	Dimensions (W × H)	398.6*251.0 (mm)	
LED IPS with Ambient	Weight	550g max	
light sensor 100% sRGB (1920 x 1080) (300 nits)	Diagonal Size	17.3 in (43.9 cm)	
	Surface Treatment	Anti-glare	
	Contrast Ratio*	800:1 (typical)	
	Refresh Rate*	60 Hz	
	Brightness [*]	300 nits (typical)	
	Pixel Resolution	Format	1920 X 1080
		Configuration	RGB Stripe
	Backlight	LED	
	PPI	128	
	Viewing Angle	85/85/85/85 (Left/	Right/Down/Up) (typical)
	* For storage drives, GB 30 GB (for Windows 10)		trillion bytes. Actual formatted capacity is less. Up to recovery software.
HP DreamColor Display	Dimensions (W × H)	398.6*230.95 (mm)	
17.3" diagonal UHD IPS	Weight	550g max	
AG - 10 (8+2) bit color	Diagonal Size	17.3 in (43.9 cm)	
(3840x2160) (400 nits) 100% AdobeRGB	Surface Treatment	Anti-glare	
	Contrast Ratio	- 1000:1 (typical)	
	Refresh Rate	60 Hz	
	Brightness*	400 nits (typical)	
	Color Gamut	100% AdobeRGB	
	Pixel Resolution	Format	3840 x 2160
	Pixel Resolution		
	Pixel Resolution	Configuration	RGB Stripe
	Backlight	Configuration RG phosphors + B-L	

Technical Specifications – Displays

	PPI	254	
	Viewing Angle	85/85/85/85 (Left/R	ight/Down/Up) (typical)
Integrate Color	Chipset	AMS TCS3430	
Calibration Sensor for HP	Sensor type	XYZ tristimulus color	imeter
DreamColor	System interface	I²C	
	Temperature range:	–30 to 85° C	
	* For storage drives, GB = 30 GB (for Windows 10) is		rillion bytes. Actual formatted capacity is less. Up to ecovery software.
17.3" diagonal UHD LED	Dimensions (W × H)	398.6*230.95 (mm)	
IPS, Touch, with Ambient	Weight	550 g (max)	
light sensor 100% sRGB (3840x2160) (400 nits)	Surface Treatment	Anti-glare	
(JOHOKE 100) (400 III(J)	Contrast Ratio	1000:1 (typical)	
	Refresh Rate	60 Hz	
	Brightness*	400 nits (typical)	
	Pixel Resolution	Format	3840 x 2160 (UHD)
		Configuration	RGB Stripe
	Backlight	LED	
	PPI	254	
	Viewing Angle	85/85/85/85 (Left/R	ight/Down/Up) (typical)
	* For storage drives, GB = 1 30 GB (for Windows 10) is r	-	illion bytes. Actual formatted capacity is less. Up to covery software.

STORAGE AND DRIVES

(III)

Internal Storage			
Intel® Optane™ Memory	Form Factor	M.2 2280	
(SSD 16 GB 2280 PCI3-3x2 NVMe 3D Xpoint)	Capacity	16 GB	
איויים אין אייין אייין אייין אייי	NAND Type	3D Xpoint	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	PCIe NVMe Gen3X2	
	Maximum Sequential Read	900 MB/s	
	Maximum Sequential Write	145 MB/s	
	Logical Blocks	28,181,188	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	L1.2	
	Must be configured with ei configured with an additio		rive or Solid-State Hybrid Drive. Cannot be
2 TB 5400 rpm SATA Hard	Drive Weight	0.21 lbs (95 g)	
Disk Drive	Capacity	2 TB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface		
	Transfer Rate	ATA-8, SATA 3.0	
		Synchronous (maximum)	
	Seek Time (typical reads, including	Single Track	1.5 ms
	settling)	Average	13 ms
		Maximum	32 ms
	Cache	128 MB	
	Rotational Speed	5400 rpm	
	Logical Blocks	3,907,029,168	
	Operating Temperature	32° to 140° F (0° to 60° C)	
	Features	ATA Security, S.M.A.R.T., N	NCQ, Ultra DMA
500 GB 7200 rpm SATA	Drive Weight	0.21 lbs (95 g)	
Hard Disk Drive	Capacity	500 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)
	Seek Time	Single Track	1.5 ms ~ 2 ms
	(typical reads, including	Average	11 ms ~ 13 ms
	settling)	Maximum	18 ms ~ 22 ms
	Cache	Up To 32 MB	-
		• • • • • • •	

Rotational Speed	7200 rpm
Logical Blocks	976,773,168
Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
Features	ATA Security, S.M.A.R.T., NCQ, Ultra DMA



1 TB 7200 rpm SATA Hard	Drivo Woight	0.21 lbs (95 g)	
Disk Drive	Capacity	1 TB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85mm)	
	Interface		
	Transfer Rate	ATA-8, SATA 3.0	600 MD/-
		Synchronous (maximum)	
	Seek Time (typical reads, including	Single Track	1.5 ms
	settling)	Average	13 ms
	-	Maximum	32 ms
	Cache	128 MB	
	Rotational Speed	7200 rpm	
	Logical Blocks	1,953,525,168	-
	Operating Temperature	32° to 140° F (0° to 60° C) [
	Features	ATA Security, S.M.A.R.T., N	CQ, Ultra DMA
500 GB Hybrid Drive,	Drive Weight	0.20 lbs (92 g) ~ 0.21 lbs (9	95 g)
8 GB cache	Capacity	500 GB	-
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	600 MB/s
	Seek Time	Single Track	2 ms
	(typical reads, including	Average	12 ms
	settling)	Maximum	22 ms
	Cache	Up to 64MB	-
	Rotational Speed	5400 rpm	
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
	Features	ATA Security, S.M.A.R.T., N	-
1 TB Hybrid Drive,	Drive Weight	90g	
8 GB cache	Capacity	1 TB	
8 GB cache	Capacity Height	1 TB 0.28 in (7 mm)	
8 GB cache			
8 GB cache	Height	0.28 in (7 mm)	
8 GB cache	Height Width	0.28 in (7 mm) 2.75 in (69.85 mm)	600 MB/s
8 GB cache	Height Width Interface	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0	600 MB/s 1.5 ms
8 GB cache	Height Width Interface Transfer Rate Seek Time (typical reads, including	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 Synchronous (maximum)	
8 GB cache	Height Width Interface Transfer Rate Seek Time	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 Synchronous (maximum) Single Track	1.5 ms
8 GB cache	Height Width Interface Transfer Rate Seek Time (typical reads, including	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 Synchronous (maximum) Single Track Average	1.5 ms 13 ms
8 GB cache	Height Width Interface Transfer Rate Seek Time (typical reads, including settling)	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 Synchronous (maximum) Single Track Average Maximum	1.5 ms 13 ms
8 GB cache	Height Width Interface Transfer Rate Seek Time (typical reads, including settling) Cache	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 Synchronous (maximum) Single Track Average Maximum Up to 128MB	1.5 ms 13 ms
8 GB cache	Height Width Interface Transfer Rate Seek Time (typical reads, including settling) Cache Rotational Speed	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 Synchronous (maximum) Single Track Average Maximum Up to 128MB 5400 rpm	1.5 ms 13 ms 32 ms
8 GB cache	Height Width Interface Transfer Rate Seek Time (typical reads, including settling) Cache Rotational Speed Logical Blocks	0.28 in (7 mm) 2.75 in (69.85 mm) ATA-8, SATA 3.0 Synchronous (maximum) Single Track Average Maximum Up to 128MB 5400 rpm 1,953,525,168	1.5 ms 13 ms 32 ms case temp]



2 TB Hybrid Drive, 8 GB cache	Drive Weight	90g		
8 GB Cache	Capacity	2 TB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum)	600 MB/s	
	Seek Time	Single Track	1.5 ms	
	(typical reads, including	Average	13 ms	
	settling)	Maximum	32 ms	
	Cache	Up to 128MB		
	Rotational Speed	5400 rpm		
	Logical Blocks	3,907,029,168		
	Operating Temperature	32° to 140° F (0° to 60° C)	[case temp]	
	Features	ATA Security, S.M.A.R.T., N	ICQ, Ultra DMA	
500 GB 7200 rpm SATA	Drive Weight	0.21 lbs (95g)		
SED FIPS-140-2	Capacity	500 GB		
compliant Hard Disk Drive	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)	
	Seek Time	Single Track	1.5 ms	
	(typical reads, including	Average	12 ms	
	settling)	Maximum	21 ms	
	Cache	32 GB		
	Rotational Speed	7200 rpm		
	Logical Blocks	976,773,168		
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]	
	Features	ATA Security; TCG Opal 2.x	, FIPS, S.M.A.R.T., NCQ, Ultra DMA	
	* FIPS-certified, hardware	-based AES-256 encryption	image.	
500 GB 7200 rpm SATA	Drive Weight	0.21 lbs (95g)		
SED Hard Disk Drive	Capacity	500 GB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)	
	Seek Time	Single Track	1.5 ms	
	(typical reads, including	Average	12 ms	
	settling)	Maximum	21 ms	



Legicity Capacity		Cache	32 MB	
Operating Temperature Features 32° to 140° F (0° to 60° C) [case temp] ATA Security, TCG Opal 2.x, S.M.A.R.T., NCQ, Ultra DMA ZES6 GB SATA TLC Solid State Drive (2.5°) Drive Weight 0.17 lb (78 g) Capacity 256 GB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Width 0.28 in (7 mm) Maximum Sequential Read Maximum Sequential Read S30 MB/s~ 560 MB/s Maximum Sequential Read Maximum Sequential Read M		Rotational Speed	7200 rpm	
Features ATA Security, TCG Opal 2.x, S.M.A.R.T., NCQ, Ultra DMA 255 6 68 SATA TLC Solid State Drive (2.5") Drive Weight 0.17 (b (78 g) Capacity 256 68 Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/0) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s~ 560 MB/s 500 MB/s~ 525 MB/s Logical Blocks 500, 11, 192 Operating Temperature 32° to 158°F (O' to 70°C) [ambient temp] Features ATA 8 Security, DIPM; TRIM; DEVSLP 1 TB SATA TLC Solid State Drive Weight 0.17 lb (78 g) Drive (2.5") Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Gapacity 158 State Drive Weight 0.28 in (7 mm) Maximum Sequential Read Maximum Sequential Read Maximum Sequential Write 530 MB/s		Logical Blocks	976,773,168	
2256 6B SATA TLC Solid State Drive (2.5") Drive Weight 0.17 (b (78 g) Capacity 256 6B Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA 8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s 500 MB/s 500 MB/s 500 mb/s 500 MB/s 500 MB/s 0perating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security; DIPM; TRIM; DEVSLP		Operating Temperature	32° to 140° F (0° to 60° C) [case ter	mp]
State Drive (2.5") Capacity 256 GB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s~ 560 MB/s 500 MB/s~ 525 MB/s 500 MB/s~ 525 MB/s Logical Blocks 500,118,192 500 MB/s~ 525 MB/s Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Features ATA Security; DIPM; TRIM; DEVSLP TB Height 0.28 in (7 mm) Juitefface Width 2.75 in (69.85 mm) Juitefface Interface ATA-8, SATA 3.0 Amamu Sequential Read Maximum Sequential Write S00 MB/s 550 MB/s 500 MB/s 500 MB/s 500 MB/s Drive (2.5") Capacity 1 TB Height 0.28 in (7 mm) Juitefface Height 0.58 in (7 mm) Juitefface ATA-8, SATA 3.0 Juitefface NAND TLC Form Factor (J/O) 2.5 inch Soo MB/s 500 MB/s 500 MB		Features	ATA Security, TCG Opal 2.x, S.M.A.I	R.T., NCQ, Ultra DMA
State Drive (2.5") Capacity 256 GB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s~ 560 MB/s 500 MB/s~ 525 MB/s 500 MB/s~ 525 MB/s Logical Blocks 500,118,192 500 MB/s~ 525 MB/s Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features Features ATA Security; DIPM; TRIM; DEVSLP TB Height 0.28 in (7 mm) Juitefface Width 2.75 in (69.85 mm) Juitefface Interface ATA-8, SATA 3.0 Amamu Sequential Read Maximum Sequential Write S00 MB/s 550 MB/s 500 MB/s 500 MB/s 500 MB/s Drive (2.5") Capacity 1 TB Height 0.28 in (7 mm) Juitefface Height 0.58 in (7 mm) Juitefface ATA-8, SATA 3.0 Juitefface NAND TLC Form Factor (J/O) 2.5 inch Soo MB/s 500 MB/s 500 MB	256 GB SATA TLC Solid	Drive Weight	0.17 lb (78 a)	
Height0.28 in (7 mm)Width2.75 in (69.85 mm)InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)2.5 inchPerformanceMaximum Sequential ReadMaximum Sequential Write S30 MB/s~ 560 MB/sS00 MB/s500 MB/s500 MB/s~ 525 MB/sLogical Blocks500,118,192500 MB/s~ 525 MB/sOperating Temperature32° to 158°F (0° to 70°C) [ambient t=mp]FeaturesATA Security; DIPM; TRIM; DEVSLPTTB SATA TLC Solid StateDrive Weight0.17 lb (78 g)Capacity1 TBHeight0.28 in (7 mm)Width2.75 in (69.85 mm)InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)2.5 inchPerformance500 MB/sS00 MB/s ~ 560 MB/s500 MB/s ~ 530 MB/sS00 MB/s ~ 510 MB/s500 MB/s ~ 530 MB/sEdgical Blocks0.002 lb (<10 g)	State Drive (2.5")	-		
Interface NAND TLC Form Factor (I/O) Performance Maximum Sequential Read Maximum Sequential Read Sol MB/s~ 560 MB/s Sol MB/s~ 560 MB/s Sol MB/s~ 500 MB/s Sol MB/s~ 502 MB/s Sol MB/s~ 500 MB/s Sol MB/s~ 500 MB/s Sol MB/s~ 500 MB/s Midth Sol Sin (7 mm) Width Sol Sin (7 mm) Width Sol MB/s ~ 500 MB/s Sol MB/s ~ 500 MB/s Features ANAND Logical Blocks Operating Temperature Sol MB/s ~ 560 MB/s Sol MB/s ~ 530 MB/s Might Mig			0.28 in (7 mm)	
NANDTLCForm Factor (I/O)2.5 inchPerformanceMaximum Sequential Read 530 MB/s~ 560 MB/sMaximum Sequential Write 530 MB/s~ 560 MB/sLogical Blocks500,118,192Operating Temperature Features32° to 158°F (0° to 70°C) [ambient +=		-	2.75 in (69.85 mm)	
Form Factor (I/O) Performance Maximum Sequential Read S00 MB/s~ 560 MB/s S00 MB/s~ 525 MB/s S00 MB/s~ 560 MB/s S00 MB/s~ 525 MB/s S00 MB/s~ 560 MB/s S00 MB/s~ 525 MB/s S00 mail Second Seco		Interface	ATA-8, SATA 3.0	
Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s~ 560 MB/s 500 MB/s~ 525 MB/s Logical Blocks 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security; DIPM; TRIM; DEVSLP T B SATA TLC Solid State Drive Weight 0.17 lb (78 g) Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance S00 MB/s~ 530 MB/s S00 MB/s~ 560 MB/s 500 MB/s~ 530 MB/s S00 MB/s~ 560 MB/s 500 MB/s~ 530 MB/s S10 MB/s ~ 560 MB/s 500 MB/s~ 530 MB/s S20 MB/s ~ 560 MB/s 500 MB/s~ 530 MB/s S20 MB/s ~ 560 MB/s 500 MB/s~ 530 MB/s S20 MB/s ~ 560 MB/s 500 MB/s~ 530 MB/s Logical Blocks 2,000,409,264 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security; DIPM; TRIM; DEVSLP Z56 GB M.2 SED TLC Solid Drive Weight 0.20 lb (<10 g)		NAND	TLC	
530 MB/s~ 560 MB/s 500 MB/s~ 525 MB/s Logical Blocks 500,118,192 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLP ATA Security; DIPM; TRIM; DEVSLP TB SATA TLC Solid State Drive Weight 0.17 lb (78 g) Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Kaxinum Sequential Read Maximum Sequential Write 530 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s 500 MB/s S00 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s 500 MB/s S00 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s 500 MB/s S00 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s 500 MB/s S00 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s 500 MB/s Edgical Blocks 0,00,409,264 500 MB/s ~ 530 MB/s Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security; DIPM; TRIM; DEVSLP Z56 GB M.2 SED TLC Solid Drive Weight 0.02 lb (<10 g) <td></td> <td>Form Factor (I/O)</td> <td>2.5 inch</td> <td></td>		Form Factor (I/O)	2.5 inch	
Logical Blocks Operating Temperature Features 32° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLP 1 TB SATA TLC Solid State Drive (2.5") Capacity 0.17 lb (78 g) Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~		Performance	Maximum Sequential Read	Maximum Sequential Write
Operating Temperature Features 32° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLP ITB SATA TLC Solid State Drive (2.5") Drive Weight 0.17 lb (78 g) Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximu Sequential Write 530 MB/s 500 MB/s 500 MB/s 500 MB/s Logical Blocks 2,000,409,264 500 MB/s 500 MB/s 500 MB/s State Drive Drive Weight 0.02 lb (<10 g)			530 MB/s~ 560 MB/s	500 MB/s~ 525 MB/s
Operating Temperature Features 32° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLP ITB SATA TLC Solid State Drive (2.5") Drive Weight 0.17 lb (78 g) Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximu Sequential Write 530 MB/s 500 MB/s 500 MB/s 500 MB/s Logical Blocks 2,000,409,264 500 MB/s 500 MB/s 500 MB/s State Drive Drive Weight 0.02 lb (<10 g)		Logical Blocks	500,118,192	
Features ATA Security; DIPM; TRIM; DEVSLP 1 TB SATA TLC Solid State Drive Weight 0.17 lb (78 g) Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Solo MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s Capacity 22° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLP Estimate Z56 GB M.2 SED TLC Solid Drive Weight 0.02 lb (<10 g)		-	32° to 158°F (0° to 70°C) [ambie	nt temp]
Drive (2.5")Capacity1 TBHeight0.28 in (7 mm)Width2.75 in (69.85 mm)InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)2.5 inchPerformanceMaximum Sequential ReadMaximum Sequential Write530 MB/s ~ 560 MB/s500 MB/s ~ 530 MB/sLogical Blocks2,000,409,264Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesATA Security; DIPM; TRIM; DEVSLPEs6 GB M.2 SED TLC SolidDrive Weight0.02 lb (<10 g)				LP
255 GB M.2 SED TLC Solid Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB	1 TB SATA TLC Solid State	Drive Weight	0.17 lb (78 g)	
Vindth 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s ~ 560 MB/s 500 MB/s 500 MB/s ~ 530 MB/s Logical Blocks 2,000,409,264 Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] Features ATA Security; DIPM; TRIM; DEVSLP Features 0.02 lb (<10 g) Capacity 256 GB Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) M.2 2280	Drive (2.5")	Capacity	1 TB	
Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Read Performance Source State Drive Grading Temperation 32 in 25 in		Height	0.28 in (7 mm)	
NAND ICC Form Factor (I/O) 2.5 inch Performance Maximum Sequential Read Maximum Sequential Read Maximum Sequential Read Sequences of the seque		Width	2.75 in (69.85 mm)	
Form Factor (I/O) Performance So MB/S - 500 MB/S CondB/S - 500 MB/S Cond		Interface	ATA-8, SATA 3.0	
Performance Maximum Sequential Read Maximum Sequential Write 530 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s 500 MB/s ~ 530 MB/s 2,000,409,264 0perating Temperature 7 2° to 158°F (0° to 70°C) [ambient +		NAND	TLC	
256 GB M.2 SED TLC Solid State Drive Drive Weight 0.02 lb (<10 g)		Form Factor (I/O)	2.5 inch	
Logical Blocks Operating Temperature Features2,000,409,264 32° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLPZ56 GB M.2 SED TLC Solid State DriveDrive Weight Capacity0.02 lb (<10 g) 256 GBHeight0.02 lb (<10 g) 256 GB0.09 in (2.3 mm) 0.09 in (2.3 mm)Width0.87 in (22 mm) 1nterfaceNANDTLC Porm Factor (I/O)Manual MatrixMatrixKate DriveMatrixManual Matrix		Performance	Maximum Sequential Read	Maximum Sequential Write
Operating Temperature Features32° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLP256 GB M.2 SED TLC Solid State DriveDrive Weight0.02 lb (<10 g)Capacity256 GBHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)M.2 2280			530 MB/s ~ 560 MB/s	500 MB/s ~ 530 MB/s
Operating Temperature Features32° to 158°F (0° to 70°C) [ambient temp] ATA Security; DIPM; TRIM; DEVSLP256 GB M.2 SED TLC Solid State DriveDrive Weight0.02 lb (<10 g)Capacity256 GBHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)M.2 2280		Logical Blocks	2.000.409.264	
256 GB M.2 SED TLC Solid Drive Weight 0.02 lb (<10 g)		-		temp]
State DriveCapacity256 GBHeight0.09 in (2.3 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)M.2 2280				
Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface ATA-8, SATA 3.0 NAND TLC Form Factor (I/O) M.2 2280		Drive Weight	0.02 lb (<10 g)	
Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)M.2 2280	State Drive			
InterfaceATA-8, SATA 3.0NANDTLCForm Factor (I/O)M.2 2280		-		
NAND TLC Form Factor (I/O) M.2 2280			0.87 in (22 mm)	
Form Factor (I/O) M.2 2280		Interface	ATA-8, SATA 3.0	
			TLC	
Performance Maximum Sequential Read Maximum Sequential Write				
		Performance	Maximum Sequential Read	Maximum Sequential Write

530 MB/s ~ 560 MB/s

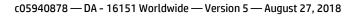
500 MB/s ~ 530 MB/s

	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TCG Opal 2.0, DIPM; T	RIM; DEVSLP	
	Datas Mataka			
512 GB M.2 FIPS-140-2 TLC Solid State Drive	Drive Weight	0.02 lb (<10 g)		
TEC Joliu State Drive	Capacity	512 GB		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Generation	Micron 1100		
	Interface	ACS-3, SATA 3.2		
	NAND Type	TLC		
	Form-Factor (I/O)	M.2 2280		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		Up to 530MB/s	Up to 400MB/s	
	Logical Blocks	1,000,215,216		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient t	empl	
	Features	ATA Security; TCG Opal 2.0; FIPS; DI	• -	
		And Security, red opar 2.0, rin 5, Di		
360GB M.2 TLC Solid	Drive Weight	0.02 lb. (10 g)		
State Drive	Capacity	360 GB		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Generation	Intel [®] Pleasant Star		
	Interface	PCIe NVMe Gen3X4		
	NAND Type	TLC		
	Form-Factor (I/O)	M.2 2280		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		Up to 1700MB/s(Compressible Performance)	Up to 600 MB/s(Compressible Performance)	
	Logical Blocks	703,282,608		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient t	emp]	
	Features	ATA Security (Option); TRIM; L1.2		
256 GB M.2 NVMe TLC	Drive Weight	0.02 lb (<10 g)		
Solid State Drive	Capacity	256 GB		
		0.09 in (2.3 mm)		
	Height	0.09 in (2.3 mm)		
	Width Concretion			
	Generation	Samsung PM961/ Toshiba XG5		
	NAND Type	TLC		
	Form-Factor (I/O)	M.2 2280		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		2580 MB/s ~ 2600 MB/s	1000 MB/s ~ 1100 MB/s	



(III)

256 GB M.2 NVMe TLC SED	Logical Blocks Operating Temperature Features Drive Weight	500,118,192 32° to 158°F (0° to 70°C) [ambient te ATA Security (Option),TRIM; L1.2 0.02 lb (<10 g)	mp]	
Solid State Drive	Capacity	256 GB		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Generation	Samsung PM961 SED Opal2/ Toshiba	a XG5 SED Opal2	
	NAND Type	TLC		
	Form-Factor (I/O)	M.2 2280		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		2580 MB/s ~ 2600 MB/s	Up to 1000 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	mp]	
	Features	ATA Security (Option); TCG Opal 2.0;	TRIM; L1.2	
512 GB M.2 NVMe TLC	Drive Weight	0.02 lb (<10 g)		
Solid State Drive	Capacity	512 GB		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Generation	Samsung PM981 / Toshiba XG5		
	NAND Type	TLC		
	Form-Factor (I/O)	M.2 2280		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		2800 MB/s ~ 2900 MB/s	1000 MB/s ~ 1800 MB/s	
	Logical Blocks	1,000,215,215		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	mp]	
	Features	ATA Security,TRIM; L1.2		
512 GB M.2 NVMe TLC	Drive Weight	0.02 lb (<10 g)		
Solid State Drive	Capacity	512 GB		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Generation	Samsung PM981 SED Opal2/ Toshiba	a XG5 SED Opal2	
	NAND Type	TLC		
	Form-Factor (I/O)	M.2 2280		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		2800 MB/s ~ 2900 MB/s	1000 MB/s ~ 1800 MB/s	
			כן נויו טעסד יי כן נויו טעסד	
	Logical Blocks	1,000,215,215		



	Operating Temperature	32° to 158°F (0° to 70°C) [ambient ter	mp]
	Features	ATA Security (Option); TCG Opal 2.0; 1	rrim; L1.2
	Duine Mainht		
1 TB, M.2 NVMe TLC Solid State Drive	-	0.02 lb (<10 g)	
State Brive	Capacity	1 TB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Generation	Samsung PM981 / Toshiba XG5	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2900 MB/s ~ 3000 MB/s	Up to 2000MB/s
	Logical Blocks	2,000,409,264	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient ter	mp]
	Features	ATA Security, TRIM; L1.2	
2 TB, M.2 NVMe TLC Solid	Drive Weight	0.02 lb (<10 g)	
State Drive	Capacity	2 TB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Generation	Toshiba XG5P	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 2900MB/s	Up to 2100 MB/s
	Logical Blocks	3,907,029,168	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient ter	lam
	Features	ATA Security, TRIM; L1.2	
	· catal C3	ATT Security, Mari, ETE	

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows[®] 10) disk is reserved for system recovery software.

Optical Drives Blu-ray R/RE DVD+/-RW

SuperMulti DL Drive Access Times Random: 200 ms CD-ROM (typical) 200 ms DVD-ROM (typical) 250 ms BD-ROM (typical) Max Data Transfer Rate 24X CD-ROM 8X DVD-ROM 24X CD-R 16X CD-RW



8X DVD+R 8X DVD+RW 6X DVD+R Dual Layer 6X DVD-R Dual Layer **5X DVD-RAM** 6X BD-ROM 6X BD-R 2X BD-RE Transfer Mode UDMA Mode 5 Interface Gen 1 SATA Supported Media (read) CD-DA, , CD-TEXT, CD-ROM, CD-ROM XA, MIXED MODE CD, CD-I, CD-I Bridge (Photo-CD, Video CD), Multisession CD (Photo-CD, CD-EXTRA, Portfolio, CDR, CD-RW), CD-R, CD-RW, DVD-ROM (DVD-5, DVD-9, DVD-10, DVD-18), DVDR, DVD-RW, DVD+R, DVD+RW. DVD-RAM, BD-ROM, BD-R, BD-RE Supported Media (write) CD-R, CD-RW, DVD+R, DVD+R DL, DVD+RW, DVD-R, DVD-R DL, DVD-RW, DVD-RAM, BD-R, BD-RE **Max Media Capacity** (read) 50.0 GB **Max Media Capacity** (write) 50.0 GB Transport Tray Loading



Technical Specifications - Security

SECURITY

HP Fingerprint Sensor Mobile Voltage Operation	3.0V-3.6V Single Supply	
Operating Temperature	14° - 167°F (-10° - 75°C)	
Current consumption image	36mA	
Low latency wait for finger	950 uA	
Capture rate	3000 lines/sec	
ESD Resistance	IEC 6100-4-2 4B (+/-15KV)	
Detection Matrix	200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm	

Smart Card Reader	Smart card standard	PC/SC 2.0 for Windows smart card standard
	Dimensions (L x W x H)	0.41x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm)
	Smart Card support	ISO 7816 Class A and AB smart cards
	Smart Card Interface	Smart Card Interface with T = 0 and T = 1 support Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM
	Operating systems	Normal Mode With card present, before being suspended: 40.9 mA Without card present, before being suspended: 33.16 mA After being suspended with smart card present: 380 µA After being suspended without smart card present: 380 µA
	Features	 Power Saving Mode: With card present, before being suspended: 40.6 mA Without card present: 380 µA After being suspended with smart card present: 380 µA Support single slot Support 10, T1 protocol Support 12C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM Support ISO7816 Class A, B and C (5V/3V/1.8V) card Implemented as an USB full speed device with bulk transfer endpoint, Mass Storage endpoint Built-in PLL for USB and Smart Card clocks requirement Support EEPROM for USB descriptors customization (PID/VID/ iManufacturer/iProduct/Serial Number), Direct Web Page Link, and accessing memory card module. EEPROM programmable via USB interface Support Direct Web Page Link via configuration in external EEPROM • Support short APDU and extended APDU Compatible with Microsoft USB-CCID driver Support USB selective suspend



Technical Specifications - Security

- Support Power Saving Mode (Using one pin to select between Normal/PWR Saving Mode)
- Support card power over current protection mechanism
- Built in resonator.
- Support USB LPM (Link Power Management) features.
- Embedded clock source.

Technical Specifications – Networking and Communications

NETWORKING/COMMUNICATIONS

Intel® I219-LM Gigabit Network Connection	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) IEEE 802.3u Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE(Energy Efficient Ethernet) IEEE 802.1as/1588 conformance Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power Management	ACPI compliant - multiple power modes Energy Detect Low Power Mode(Green Ethernet)
	Management Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload(ARP & NS) Large send offload and Giant send offload Receiving Side Scaling MACSec Offload (802.3ae) Intel [®] vPro [™] iSCSI Boot RSS (Receive Side Scaling) Ultra Low Power
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ. NOTE: Intel® I219-LM Gigabit interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.
	NIC Device Driver Name	Intel [®] Ethernet Network Connection I219-LM



Technical Specifications – Networking and Communications

Intel®XMM™ 7360 LTE- Advanced	Technology/Operating Bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless Protocol Standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B and XTRA)
	GPS Bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum Data Rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum Output Power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum Power Consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	5.8g
	Dimensions	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)
	(Length x Width x Thickness)	

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.



Technical Specifications – Networking and Communications

HP lt4132 LTE/HSPA+ w/GPS	Technology/Operating bands	LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 800 MHz (Band 20, DD800) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 8 LTE Specification WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9
	GPS	Standalone, A-GPS
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
	Maximum data rates	LTE: 100 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm E-GPRS 1900/1800: 26.5 dBM E-GPRS 900/850: 27.5 dBM GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	6 g
	Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.



Intel® Dual Band Wireless-AC 9560AC 802.11 a/b/g/n/ac (2x2) WiFi + Bluetooth 5.0 Combo Adaptor*	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac	
	Interoperability	Wi-Fi certified	
	Frequency Band	802.11b/g/n	2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
		802.11a/n	4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: No support for this band in Indonesia
	Data Rates	802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15 (20MHz and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80M	
	Modulation	Direct Sequence Spread Spect CCK, BPSK, QPSK, 16-QAM, 64	
	Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, ar WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX WAPI 	
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point R	equired)
	Roaming	IEEE 802.11 compliant roamir	ng between band Access Points
	Output Power ²	802.11b : +16dBm minimum 802.11g : +14dBm minimum 802.11a : +14dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +12dBm minimum 802.11n HT20(5GHz) : +14dBm minimum 802.11n HT40(5GHz) : +12dBm minimum	
	Power Consumption	Transmit: 2.0 Watts Receive: 1.6 Watts Idle mode: 180 mW (WLAN As Idle mode: 50 mW (WLAN una Connect Standby: 10 mW (W Radio disabled: 5 mW	ssociated)



Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant power saving mode		
Receiver Sensitivity ³			
	802.11b, 11Mbps : -86dBm m		
	802.11g, 6Mbps : -88dBm ma		
	802.11g, 54Mbps : -74dBm m		
	802.11a, 6Mbps : -88dBm ma		
	802.11a, 54Mbps : -74dBm m 802.11n, MCS07 : -69dBm ma		
	802.11n, MCS15 : -66dBm ma		
	802.11ac, 1SS, MCS-0 : -86dE		
	802.11ac, 1SS, MCS-9:-61dE		
	802.11ac, 2SS, MCS-0 : -83dE		
	802.11ac, 2SS, MCS-9 : -58dE	3m maximum	
Antenna Type	High efficiency antenna with enclosure	spatial diversity, mounted in the display	
		I/5 GHz antennas are provided to the card to	
		nications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Or		
	Type 1630 : 2.3 x 16.0 x 30.0	mm	
Weight	Type 2230 : 2.8g		
	Or		
	Type 1630 : 2g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	Temperature	
Humidity	Operating Non-operating	Humidity	
Altitude	Operating Non-operating	Altitude	
LED Activity		Nhite Padie ON	
LED Activity	LED Amber - Radio OFF; LED White - Radio ON		

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

* Wireless access point and internet service required. Availability of public wireless access points limited.

HP Integrated Module with Bluetooth 4.2 Wireless Technology

Bluetooth Specification	4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)



	Transmit Power			e as a Class II Bluetooth dev	vice witl
	Receiver Sensitivity	a maximum transmi	t power of + 4 dBm	for BR and EDR.	
		Modulation	0.01% BER	0.001% BER	
		GFSK π/4-DQPSK	-80 dBm -80 dBm	-70 dBm -70 dBm	
		8DPSK	-80 dBm	-70 dBm	
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 1	7 mW		
	Range	Legacy Up to 33 ft ([.] BLE Up to 99 ft (30 r			
	Electrical Interface	USB 2.0 compliant Microsoft Windows® Bluetooth Software			
	Bluetooth Software Supported				
	Link Topology	Point to Point, Multi	point Pico Nets up t	o 7 slaves	
	Security	Point to Point, Multipoint Pico Nets up to 7 slaves Full support of Bluetooth Security Provisions			
	Power Management	Microsoft Windows® ACPI, and USB Bus Support Self-configurable to optimize power conservation in all operating mode including Standby, Hold, Park, and Sniff All necessary regulatory approvals for supported countries, including:			
	,				modes,
	Certifications				ling:
		FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950			
		UL, CSA, and CE Mar			
	Pluataath Drafilac				
	Bluetooth Profiles Supported				
Near Field Communications (NFC) Controller (optional)	Controller Supports	Windows 7,NFC Forum	Proximity Events PC/SC		
	Dimensions (L x W x H)	Module 25 mm by 10) mm by 2.0 mm		

Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
Chipset	NPC100
System interface	12C
NFC RF standards	standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2



NFC Forum Support Tag Reader	Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 (PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards		
Card Emulation	(PICCVICC)		
Mode	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa		
Frequency	13.56 MHz		
NFC Modes Supported	Reader/Writer, Peer-to-Pe	er	
Raw RF Data Rates	106, 212, 424, 848 kbps		
Operating temperature	0°C to 70°C		
Storage temperature	-20°C to 125°C		
Humidity	10-90% operating 5-95%	non-operating	
Supply Operating voltage	2.97 to 5.5 Volts		
I/O Voltage	1.8V or 3.3V		
Power Consumption	Booster enable, VBAT= 3.3V,		
	VCC_BOOST = 5V) Mode Power Consumption,	Typical ² Polling 7.3 mA Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA Detected Test Tag Type 4 Total 282.3 mA Net Module 235.3 mA	
Antenna connector Notes	 0.5mm pitch, 7 connector FPC. Antenna matching is external to module. With application or UICC support Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured. 		



Technical Specifications – Audio and Multimedia

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Function Key Volume Controls	Volume up, volume down, and mute
rull Duplex	Yes
Microphone In	Stereo
Headphone/Line Out	Stereo
ntegrated Microphone	Yes, three digital microphone array when equipped with optional webcam
Frequency Response	20 Hz - 20 kHz
Signal to Noise Ratio	106dB (DAC), 102dB (ADC)
Total Harmonic Distortion	91dB THD+n on LineOut/HP (0.003%)
Noise Floor	-110 dB
Play Sampling Rate (s)	Up to 192kHz
Record Sampling Rate(s)	Up to 96kHz
DAC	16, 20 or 24-bit
ADC	16, 20 or 24-bit
Power Rating	1 Watt/per speaker
Impedance	8 ohms/per speaker
	Headphone/Line Out ntegrated Microphone Frequency Response Signal to Noise Ratio Total Harmonic Distortion Noise Floor Play Sampling Rate(s) Record Sampling Rate(s) DAC ADC

Technical Specifications – Environmental

POWER

HP 200W Slim Smart AC Adapter	Dimensions Weight Input Output	(165 x 79 x 25.4 mm) 530 g 100 to 240 VAC Input Efficiency Input frequency range Input AC current Output power	88% min at 115 VAC 47 to 63 Hz 2.9 A at 90 VAC, 1.45 A at 90 VAC 200W	
		DC output Hold-up time Output current protection Over voltage protection	19.5V 5 msec at 115 VAC input 16A max auto-recovery 29V max automatic shutdown	
	Connector	3 pin/grounded, 4.5mm ba	arrel type	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
		Altitude	0 to 16404 ft (0 to 5,000 m)	
		Storage Humidity	10% to 95%	
	EMI and Safety Certifications	CE Mark- full compliance with LVD and EMC directives; Worldwide safety standards- IEC950, EN60950, UL1950, Class 1, SELV; Agency approvals- C- UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCIB, NOM-1 NYCE; MTBF- over 200,000 hours at 25°C ambient condition.		
HP Long Life 6-cell Polymer Battery (96 WHr)	Dimensions (H x W x L) Weight (max) Cells/Type Energy	Weight (max)1.12lb (420g)Cells/Type6-cell; Polymer		
		Amp-hour capacity	8.42Ah	
		Watt-hour capacity	96Wh	
	Temperature	Operating (Charging) Operating (Discharging) Non-operating	32° to 113° F (0° to 45° C) 14° to 140° F (-10° to 60° C) -4° to 140° F (-20° to 60° C)	
	Battery Re-Charge Time	System in OFF or Standby Mode	3 hours	
		System ON	3 to 5 hours	
	Fuel Gauge LED	No		
	Warranty*	3 year 0.7C; HP Fast Charge 90% charge in 90 minutes		
	Charge Rate			
	Compatible with optional Travel Battery	l N/A		
	* 3-year platform warrant	y is required for a 3-year Lo	ng Life Battery warranty.	



Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. 			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Sort idle)	21.34 W	21.54 W	21.31 W	
Normal Operation (Long idle)	9.94 W	10.51 W	10.55 W	
Sleep	1.29 W	1.42 W	1.32 W	
Off	0.47 W	0.53 W	0.47 W	
	Energy efficiency data listed is for an model family. HP computers marked applicable U.S. Environmental Prote computers. If a model family does n energy efficiency data listed is for a efficiency power supply, and a Micro	l with the ENERGY STAR® L ction Agency (EPA) ENERG ot offer ENERGY STAR® co typically configured PC fea	ogo are compliant with the Y STAR® specifications for mpliant configurations, then aturing a hard disk drive, a high	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	73 BTU/hr	74 BTU/hr	73 BTU/hr	
Normal Operation (Long idle)	34 BTU/hr	36 BTU/hr	36 BTU/hr	
Sleep	4 BTU/hr	5 BTU/hr	5 BTU/hr	
Off	2 BTU/hr	2 BTU/hr	2 BTU/hr	
	*NOTE: Heat dissipation is calculated attained for one hour.	d based on the measured v	vatts, assuming the service level is	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{wAd} , bels)		Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	2.8		16	
Fixed Disk – Random writes	3.2		24	
Optical Drive – Sequential reads	5			
Longevity and Upgrading	This product can be upgraded, possi features and/or components contain			
	 4 USB ports 2 Thunderbolt[™] 3 ports 2 2.5" Storage Bay Drives 2 M.2 SATA SED Solid State Drive 1 Smart Card Reader 	S		



Technical Specifications – Environmental

	 1 SD Card re 4 SODIMM n 1 HDMI 1.4 p 	nemory slots		
	Spare parts are of production.	e available throughout the warranty period and or for up to "5	" years after the end	
Batteries	This battery(s)	in this product comply with EU Directive 2006/66/EC		
	Mercury gr	in the product do not contain: eater the1ppm by weight greater than 20ppm by weight		
	Battery type: L	R2O32 (coin cell) ithium -cell high capacity Lithium-Ion battery		
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. 			
	 This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net 			
	 Plastic ISO10 This p 	cs parts weighing over 25 grams used in the product are mark)	
Packaging Materials	External:	PAPER/Corrugated	373 g	
	Internal:	PLASTIC/Polyethylene Expanded - EPE	64 g	
		PLASTIC/Polyethylene low density – LDPE PAPER/Paper	33 g 92 g	
		ackaging material contains at least 81.5% recycled content. ed paper packaging materials contains at least 80.0% recycle	ed content.	
Material Usage	This product do to the HP Gene	pes not contain any of the following substances in excess of re ral Specification for the Environment at .com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):		
	 Certai Cadmi Chlorid Chlorid Forma Halogo Lead o Lead a Mercu Nickel handle 	n Azo Colorants n Brominated Flame Retardants – may not be used as flame r		



Technical Specifications – Environmental

	 Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Display	HP DreamColor Z31x Studio Display	Z4Y82A8
Memory	HP 4GB DDR4-2666 SODIMM	TBD
	HP 8GB DDR4-2666 SODIMM	TBD
	HP 16GB DDR4-2666 SODIMM	TBD
	HP 8GB DDR4-2666 ECC SODIMM	TBD
	HP 16GB DDR4-2666 ECC SODIMM	TBD
Cases	HP 17" Business Top Load Case	2UW02AA
	HP 17" Business Backpack	2SC67AA
Docking	HP USB-C Universal Dock	1MK33AA
	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt™ Dock 230W G2	2UK38AA
	HP Thunderbolt Dock Audio	3AQ21AA
	HP USB-C Dock G4	3FF69AA#xxx
	HP TB Dock G2 w/Combo Cable	3TR87AA#xxx
	HP Travel Hub	ТОКЗОАА
	HP 3005pr USB 3.0 Port Replicator w/ USB-C™ Adapter	Y4H06AA
Input/Output -	HP Wireless Premium Mouse	1JR31AA
Mice	HP USB Premium Mouse	1JR32AA
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP USB Travel Mouse	G1K28AA#xxx
	HP Comfort Grip Mouse	H2L63AA
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	ТбТ8ЗАА
	HP Wireless (Link-5) Keyboard	T6U20AA
Power Adapters	HP 200W SLIM Smart AC Adapter	4SC19UT#xxx
Battery	ZBook G5 Replacement Battery 96Whr Battery	TBD
Adapters	HP HDMI to DVI adapter	F5A28AA
	HDMI to VGA Adapter	H4F02AA
	USB 3.0 to RJ45	N7P47AA
	HP USB-C™ to VGA Adapter	N9K76AA
	USB-C to RJ45	V7W66AA
	HP USB-C™ to USB Hub	Z6A00AA



Options and Accessories (sold separately and availability may vary by country)

Storage - External	HP 256GB M2 NVME PCIe SSD (2280)	V3K66AA
Storage	HP 512GB M2 NVME PCIe SSD (2280)	V3K67AA
	HP 256GB TLC PCI-e 3x4 NVMe M.2 SSD	1FU87AA
	HP 512GB TLC PCI-e 3x4 NVMe M.2 SSD	1FU88AA
	HP USB External DVDRW Drive	F2B56AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Dual Head Keyed Cable Lock	1AJ41AA
	HP Docking Station Cable Lock	AU656AA#XXX
	HP Keyed Cable Lock	T0Y14AA
	HP Combination Lock	TOY15AA
	HP Essential Combination Lock	T0Y16AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Cable Lock (Non-Master key)	T1A64AA
	HP Dual Head Cable Lock (Master Key)	T1A65AA
	HP 3 year Next business day onsite Hardware Support w/Accidental Damage Protection-G2 for Notebooks	UF631E
Collaboration	HP Elite Presenter Mouse	2CE30AA#xxx
	HP UC Conferencing Keyboard	K8P74AA#xxx
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA#xxx
	HP Wireless Premium Keyboard	Z9N41AA#xxx



Summary of Changes

Date of change:	Version History:		Description of change:
May 30, 2018	From v1 to v2	Changed	Environmental Data
June 7, 2018	From v2 to v3	Changed	Format Changes
June 26, 2018	From v3 to v4	Changed	Front view, Processors, Storage and Drives, Software and Security, Power, System Unit, Security sections and format changes
August 27, 2018	From v4 to v5	Changed	Format



Copyright © 2018 HP Development Company, L.P.

The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. Intel, Core, vPro, Xeon, Celeron and Thunderbolt are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth is a registered trademark of its proprietor, used by HP Inc. under license. Adobe is a trademark of Adobe Systems Incorporated. Qualcomm and Snapdragon are trademarks of Qualcomm, Inc. ENERGY STAR is a registered trademark of Adobe Systems Incorporated. Qualcomm and Snapdragon. Microsoft and Windows are registered trademarks of Microsoft Corporation in the U.S. Environmental Protection Agency. Microsoft and Windows are registered trademarks of Microsoft Corporation in the United States and/or other countries. AMD, Enduro and FirePro are trademarks of Advanced Micro Devices, Inc. NVIDIA, the NVIDIA logo, Optimus and Quadro are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. SD, SDHC, and SDXC are trademarks or registered trademarks of SD-3C in the United States, other countries or both. USB Type-C and USB-C are trademarks of USB Implementers Forum. DisplayPort[™] and the DisplayPort[™] logo are trademarks owned by the Video Electronics Standards Association (VESA[®]) in the United States and other countries.

